

CYPRESS SEMICONDUCTOR

PRODUCT CHANGE NOTIFICATION

PCN: 000002

DATE: January 24, 2000

Subject: Moisture Sensitivity Level Change, 28-lead SOJ and SOIC packages

To:

Category:

Level:

Description of change:

Cypress has changed the packaging method on all 28-lead SOJ, and 28-lead SOIC products assembled at Cypress Semiconductor Philippines (CSPI) to drypack, Moisture Sensitivity Level 3 per JESD22-A112 as of October 1999, WW9941. This change was made as a result of customer feedback of a few instances of package delamination after board assembly.

The mold compound currently used for these products is Sumitomo EME6300HR. Cypress has qualified 2 additional molding compounds, Sumitomo EME6600 (PCN990021) and the Hitachi CEL9200 (PCN990039), and may evaluate and qualify additional molding compounds before deciding which one affords the highest level of moisture resistance and manufacturability. Cypress expects to make a final molding compound choice in Q1 2000, and will at that time begin using this new molding compound to assemble all 28-lead SOJ and SOIC packages manufactured at CSPI. During the phase-in period, all product will be dry-packed. Once Sumitomo EME6300HR has been purged from the line, and confidence is established with the new mold compound, all 28-lead SOJ and SOIC product from CSPI will revert to MSL 1 shipping status.

Please note that this change affects only 28-lead SOJ and SOIC product assembled at our CSPI facility. No MSL changes have been made for similar products assembled at our other manufacturing sites.

Cypress part numbers affected:

The following part numbers supplied in 28-lead 300-mil SOJ (package code 'V') and 28-lead SOIC (package code 'SN') packages and assembled at CSPI:
CY62256*, CY6264*, CY7C1399*, CY7C195*, CY7C196*, CY7C199*, CY7C419*, CY7C421*,
CY7C425*

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Customer part numbers affected:

Benefit of change:

Improved quality and reliability.

Qualification status:

Not applicable.

Sample status:

Not applicable.

Approximate Implementation Date:

Cypress changed the packaging method on all 28-lead SOJ, and SOIC products to drypack Level 3 per JESD22-A112 as of October 1999, WW9941.

Response Required:

No response required.

For any additional information regarding this change, please contact your local sales representative.

Sincerely,

Jim Townsend
Business Process Manager